

The background of the slide is a composite image. The upper portion shows several circular, multi-layered biological structures, possibly cross-sections of cells or spores, with a textured, concentric appearance. The lower portion shows a pile of white, translucent, cubic crystals, likely calcium fluoride or a similar material used in detectors. The overall background is dark, making the white text and light-colored images stand out.

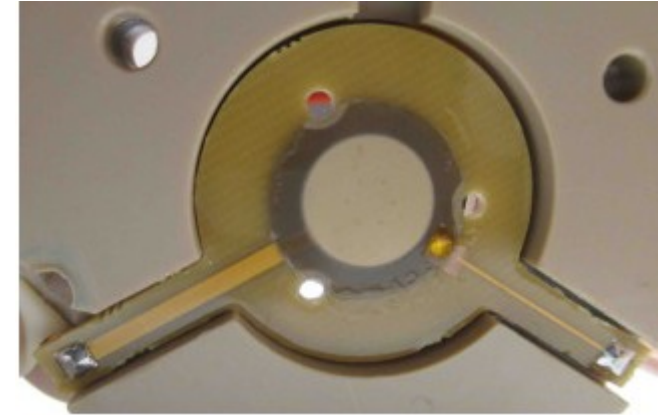
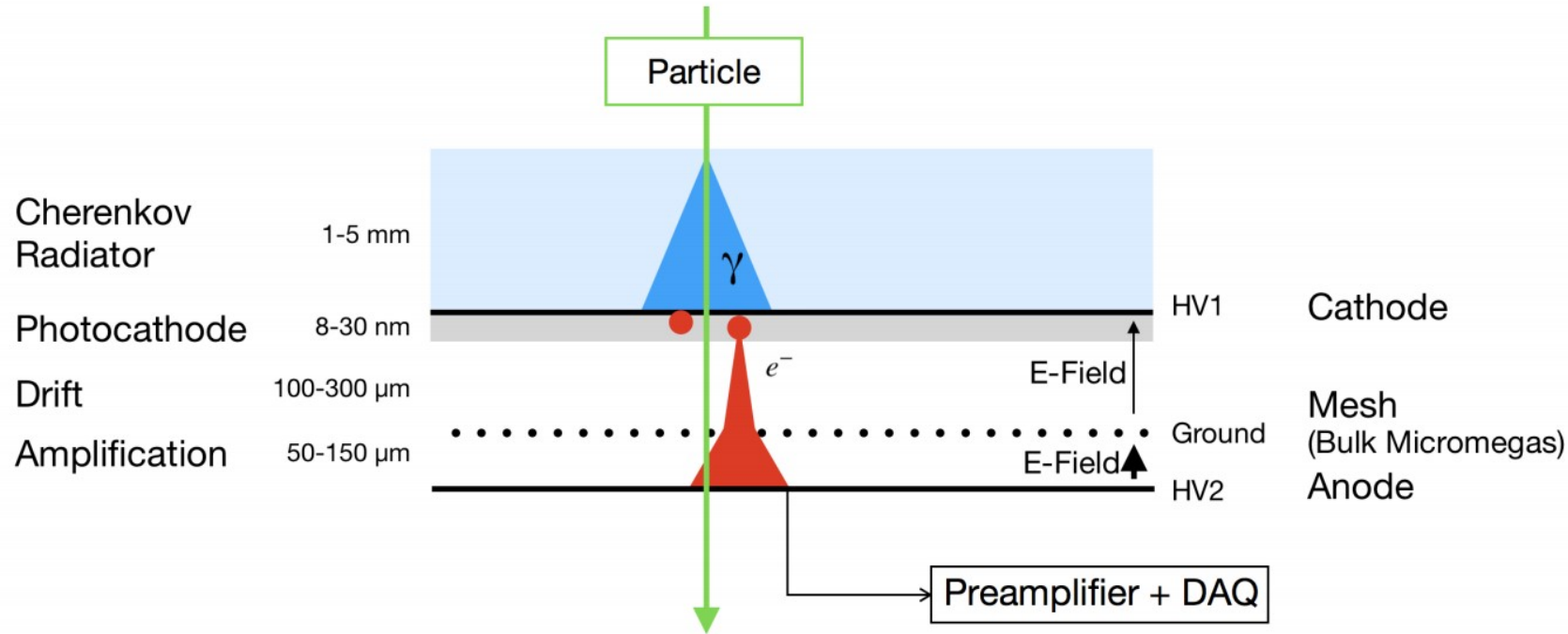
# Assembly and gain uniformity measurements of a new large area PICOSEC detector

Antonija Utrobičić

on behalf of the CERN EP-DT-DD GDD group and of the PICOSEC collaboration

RD51 Collaboration Meeting, February 16, 2021

# PICOSEC detector concept

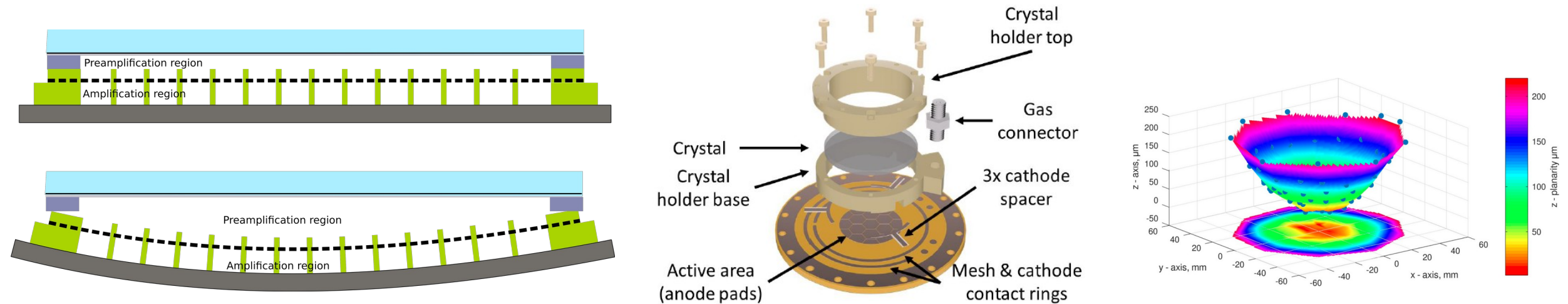


- **Purpose:** give **precise timing** information in the passage of the particle. Timing resolution of order of tens ps.
- **Cherenkov radiator:** passage of relativistic charged particle creates UV photons.
- **Photocathode:** conversion of UV photons into electrons.
- **Drift /preamplification region:** Preamplification of electrons in high drift field region (  $\sim 20$  kV/cm)
- **Anode/amplification region:** final electron amplification in high electric field ( $\sim 40$  kV/cm)
- Arrival of the amplified electrons to the anode creates a signal.
- First single pad detector prototype  $\rightarrow$  time resolution below 25 $\sim$ ps.



# First picosec multipad detector

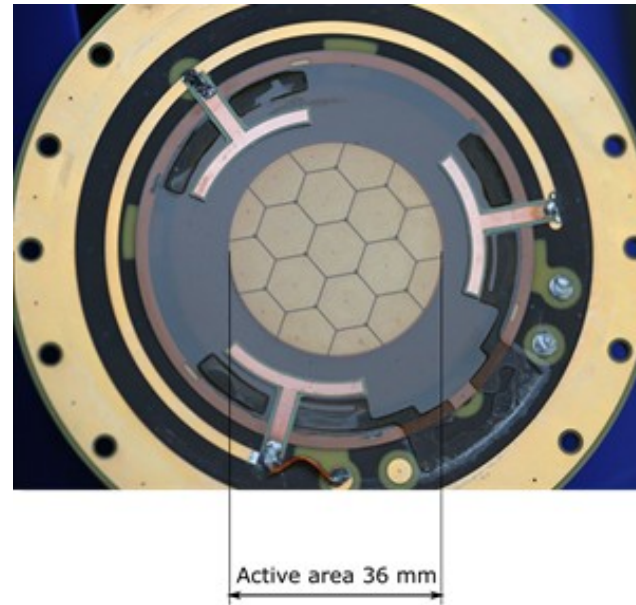
- **Drift/ preamplification region:** similar thickness ( $\sim 150 \mu\text{m}$ ) and similar electric field as amplification.
- Uniform detector response  $\rightarrow$  uniform gap over entire active area.
  - Change in a drift gap thickness  $\rightarrow$  change in the **drift field** and **length** of preamplification avalanche evolution.
  - This would affect detector gain and timing performance.
- **First multi pad PICOSEC detector:** observed deformations in range of  $30 \mu\text{m}$  in active area (due to the attachment to the chamber & non flatness of the board itself).
- Gap height difference of  $15 \mu\text{m}$  would result in time error of  $100 \text{ ps}$ .



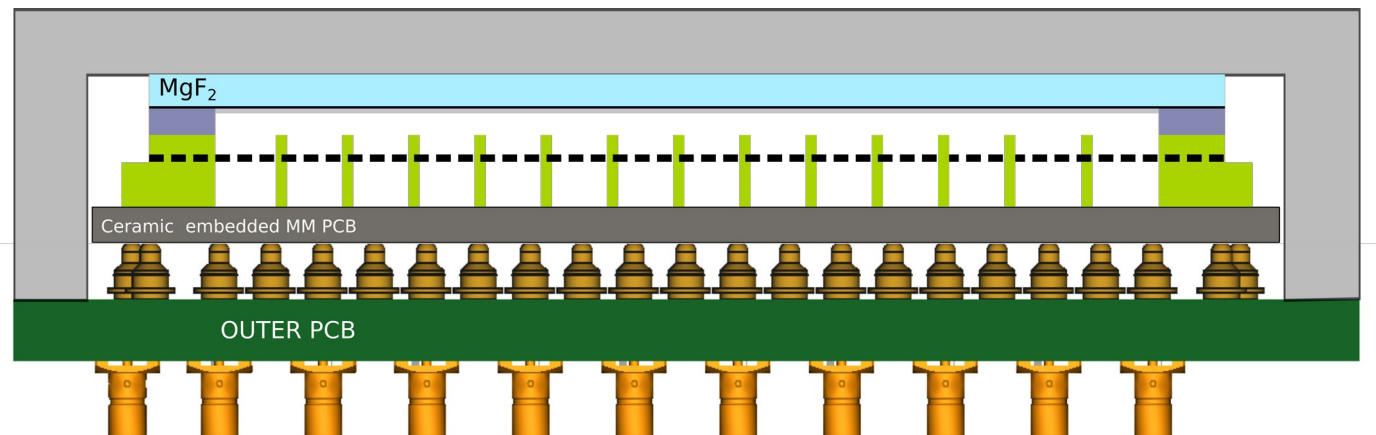
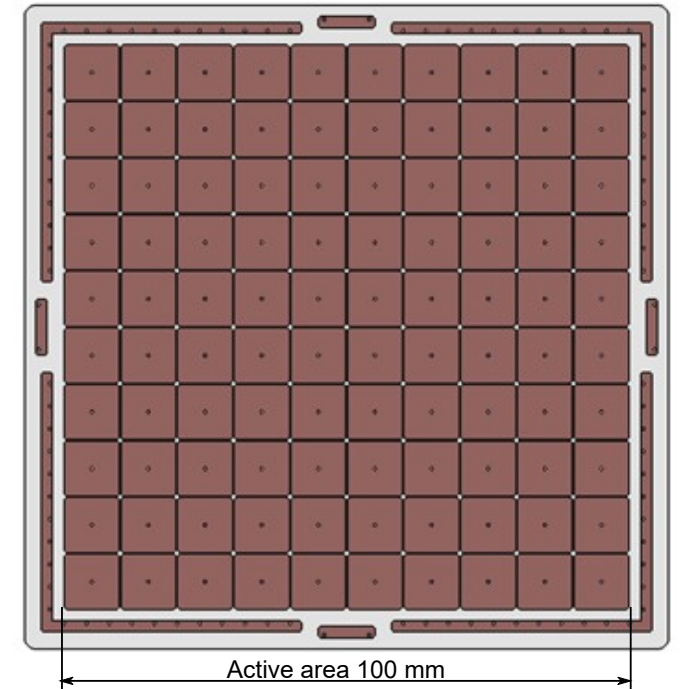
# Towards new PICOSEC multipad

- Increase in active area ( $\approx 10$  times) AND number of channels (19  $\rightarrow$  100)
- Much larger active area  $\rightarrow$  deformation will be even more pronounced.
- Main challenge: make detector with uniform gaps (below 10  $\mu\text{m}$ ) over the entire 10 cm x 10 cm active area.
  - Detach the Micromegas board from the housing.
  - Micromegas board with planarity in 10  $\mu\text{m}$  range over the entire active area.

First PICOSEC MM board

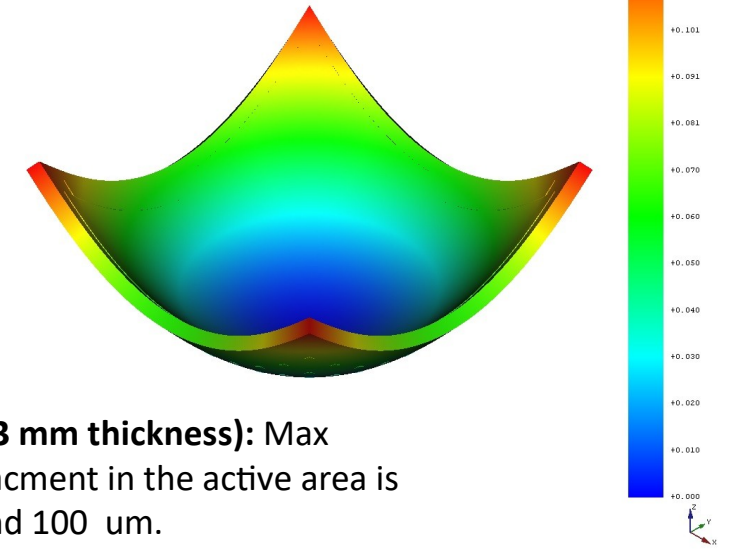
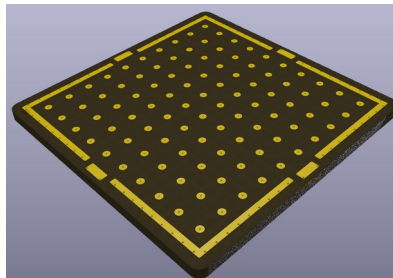
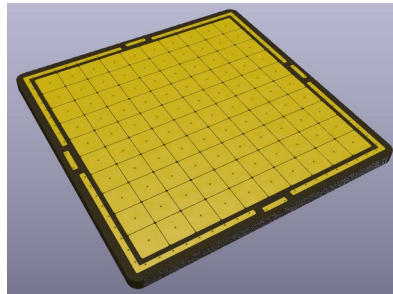
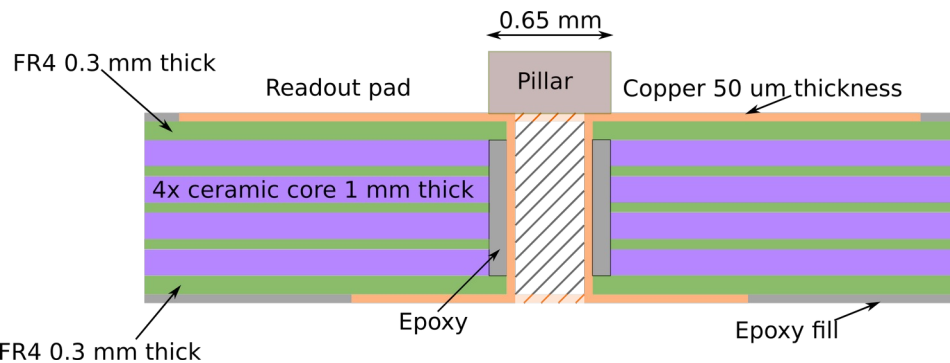


New larger area PICOSEC MM board

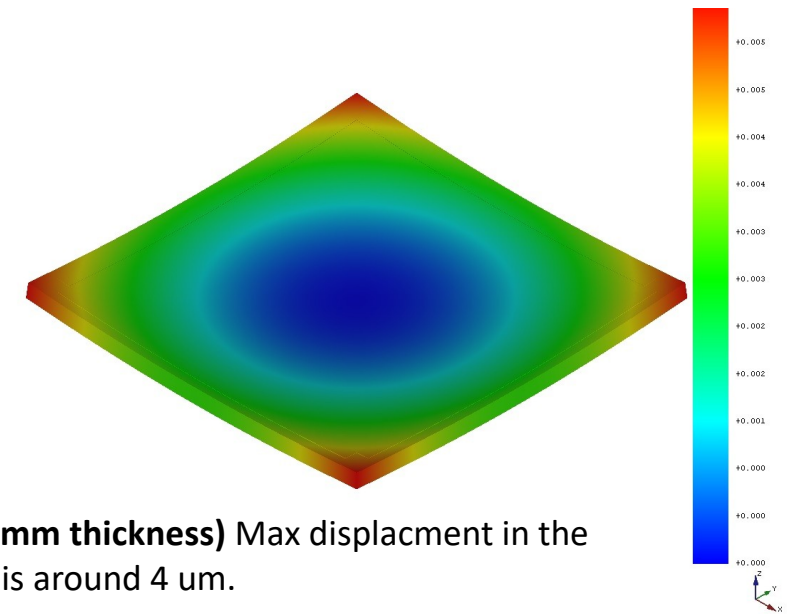


# Planarity simulation driven design of MM PCB

- Structural simulation of board deformations under mesh tension resulted in the usage of a thicker board stack and more rigid core material.
- **Material:** hybrid ceramic instead FR4
- **Thickness:** 4,85 mm instead of 3 mm.
- **Design requirements:** PCB flatness within 10 um over the active area.
- Objective: follow the manufacturing process and conduct the planarity measurements on each of the production steps.



**FR4 (3 mm thickness):** Max displacement in the active area is around 100 um.



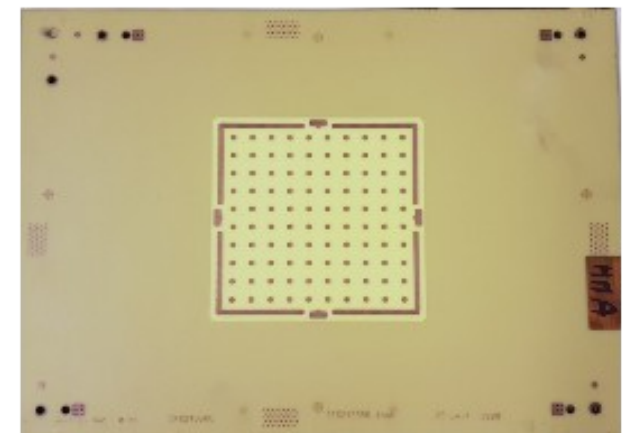
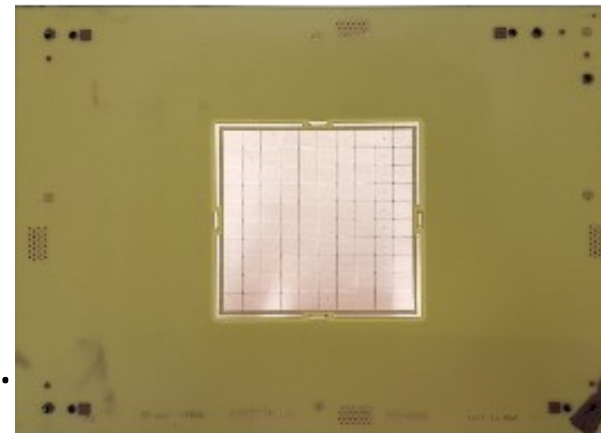
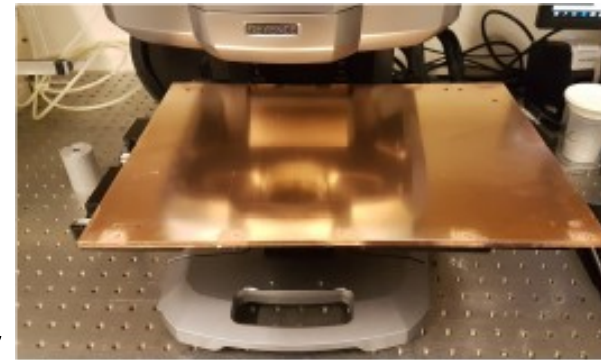
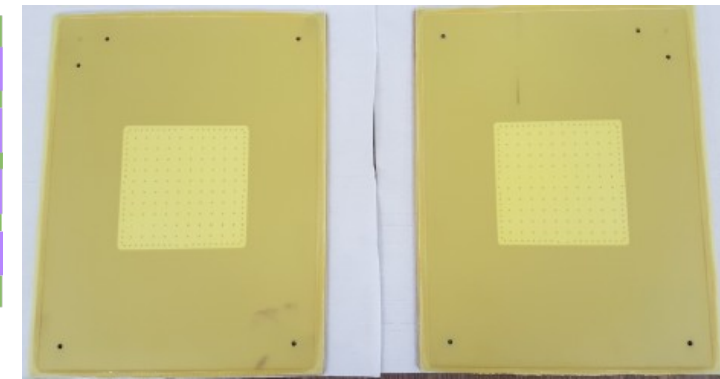
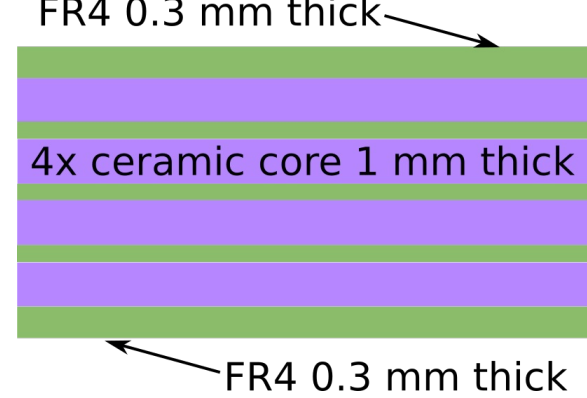
**Ceramic (4 mm thickness)** Max displacement in the active area is around 4 um.

More details on new PICOSEC planarity simulations:  
Antonija Utrobicic, RD51 CM June 2020,  
<https://indico.cern.ch/event/911950/sessions/348123/#20200626>



# Picosec Mircomegas: anode board production

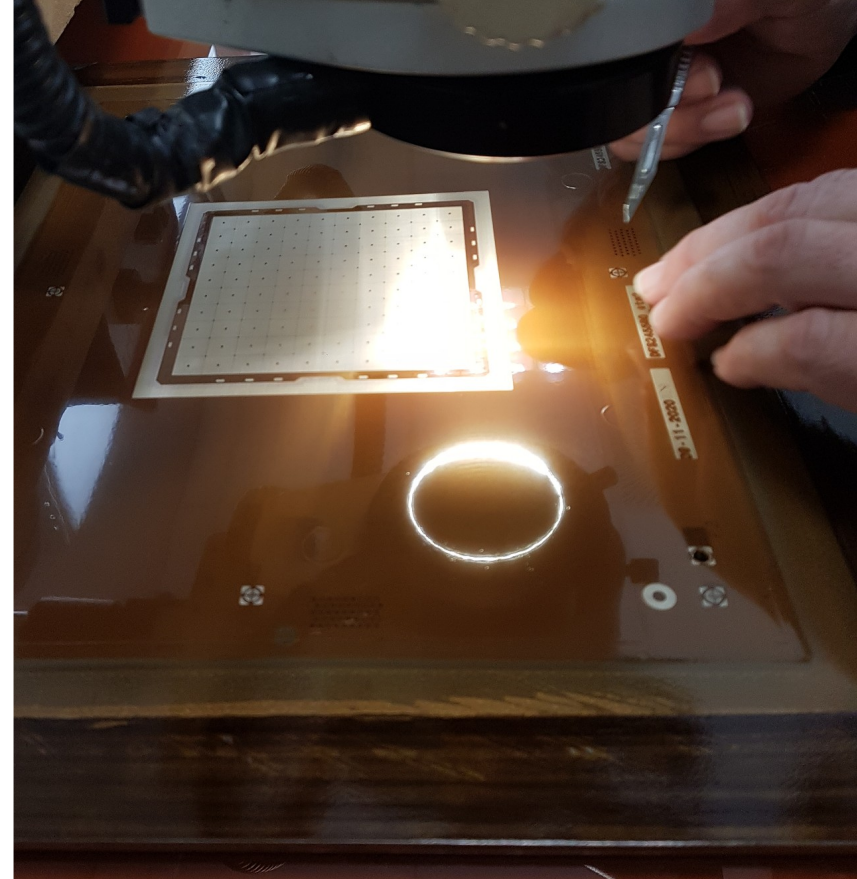
- 1. Production of the ceramic substrate:** gluing 4x1 mm ceramic boards and covering with 0,3 mm thin FR4 layer on top and bottom side.
  - Polishing of the top side FR4 layer-> planarity measurements.
  - Planarity below 15 um (MMB) and 23 um (MMA).
- 2. Epoxy coating and copper deposition** (55 um) on the top and bottom side of the board.
  - Planarity measurements → polishing → planarity measurements.
  - Planarity below 9 um (MMB) and 11,5 um (MMA).
- 3. Copper etching.**
  - Planarity below 7,8 um (MMB) and 7,2 um (MMA).
- 4. Epoxy fill between the copper traces/readout pads and polishing.**
  - Planarity below 7,6 um (MMB) and 8 um (MMA).



Top side / PADs side

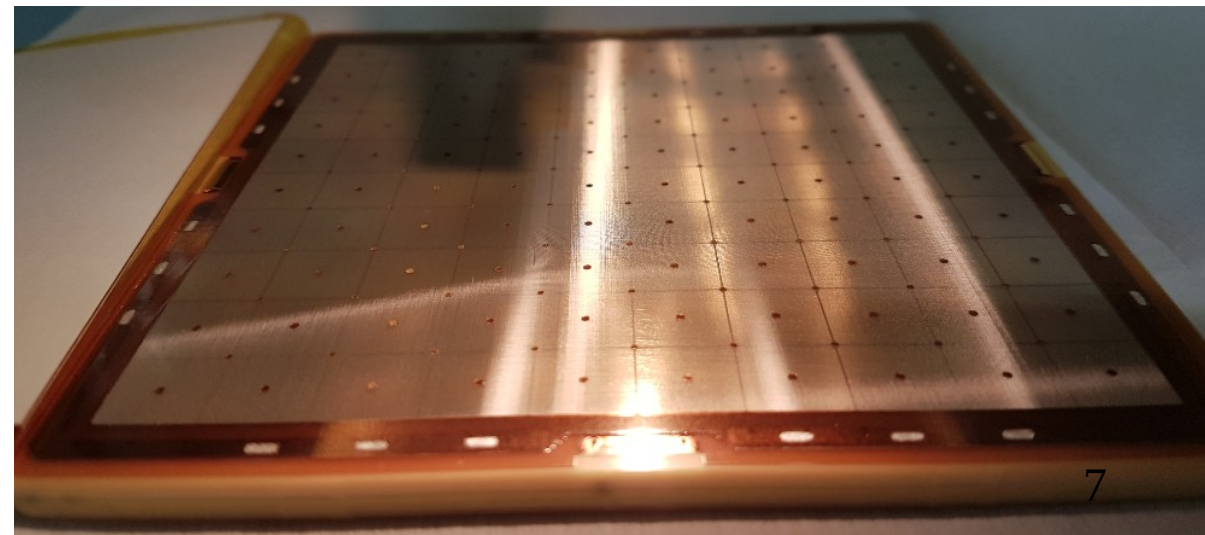
Bottom side / Pogo pins side





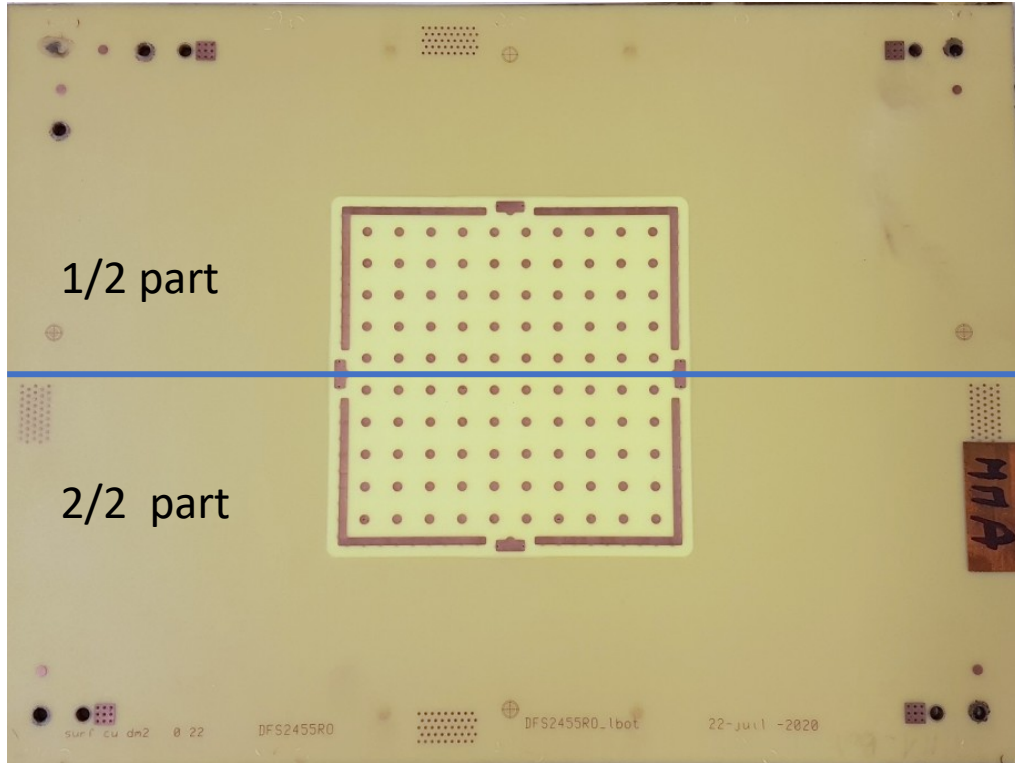
# Micromegas bulking

Huge thanks to Rui, Antonio, Olivier and Bertrand! 😊





# Picosec Micromegas: back side board planarity measurements



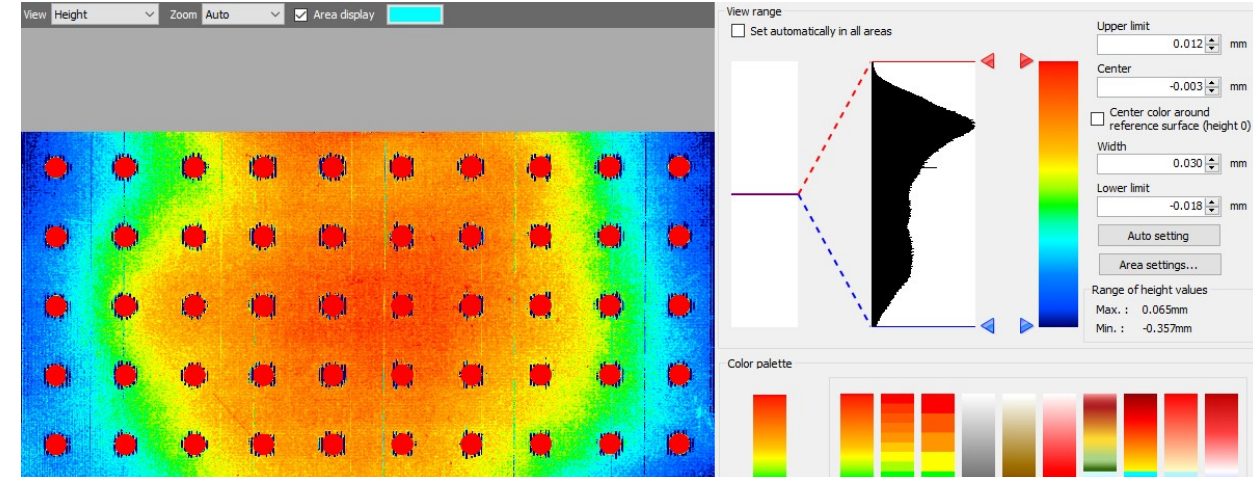
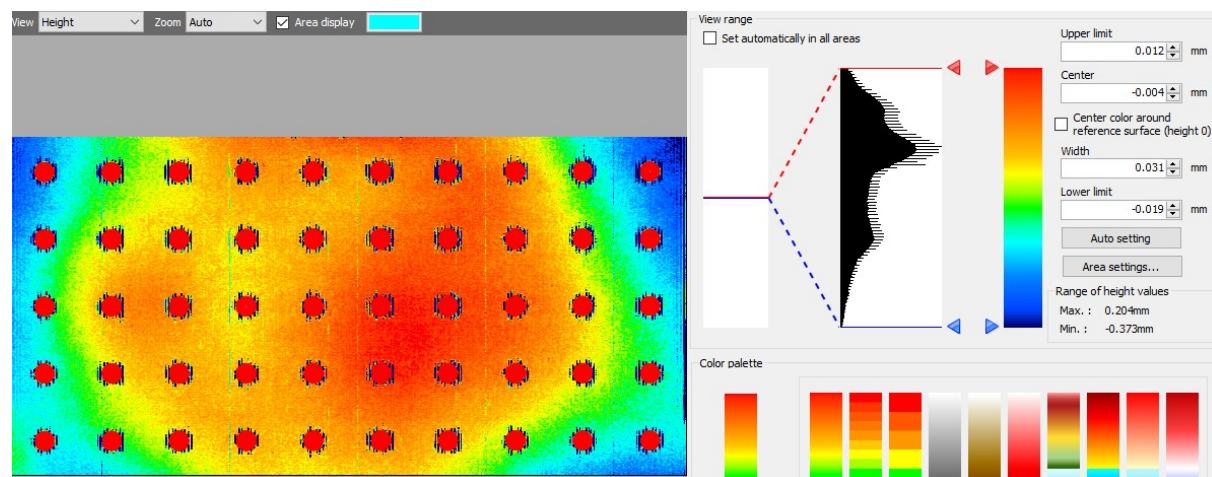
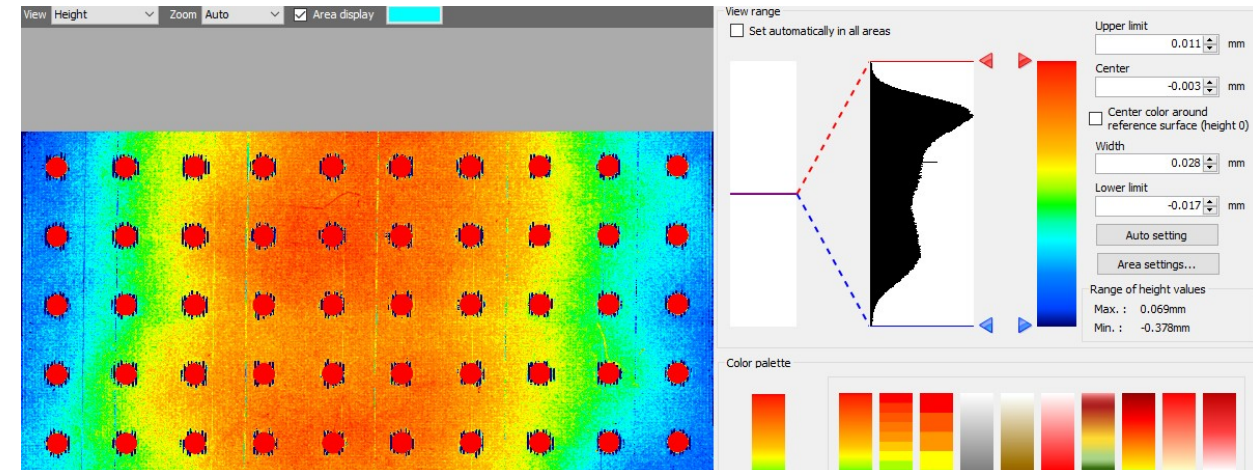
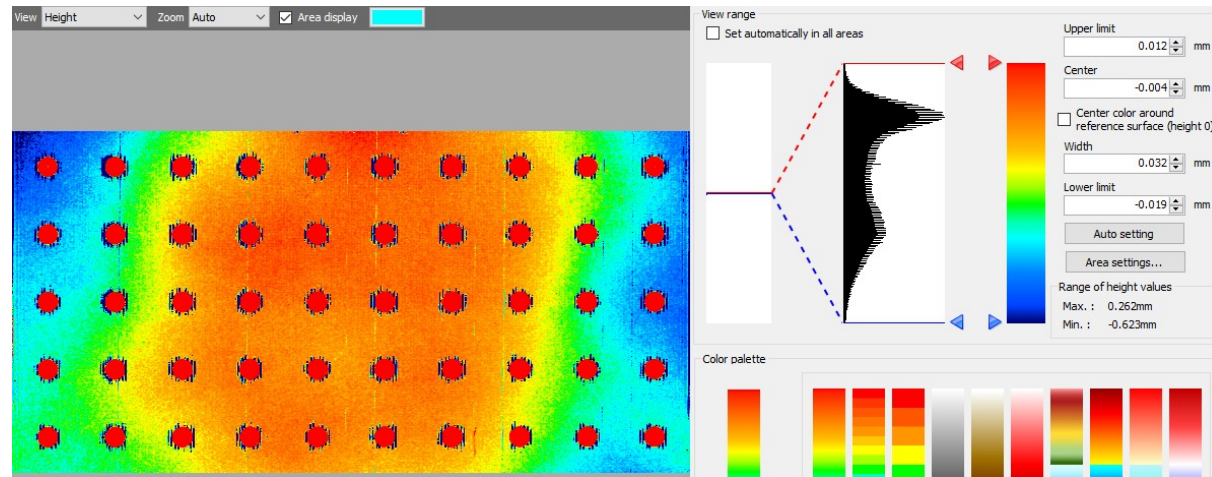
Back side of the board before bulking



Back side of the board after bulking



# Picosec Micromegas planarity measurements

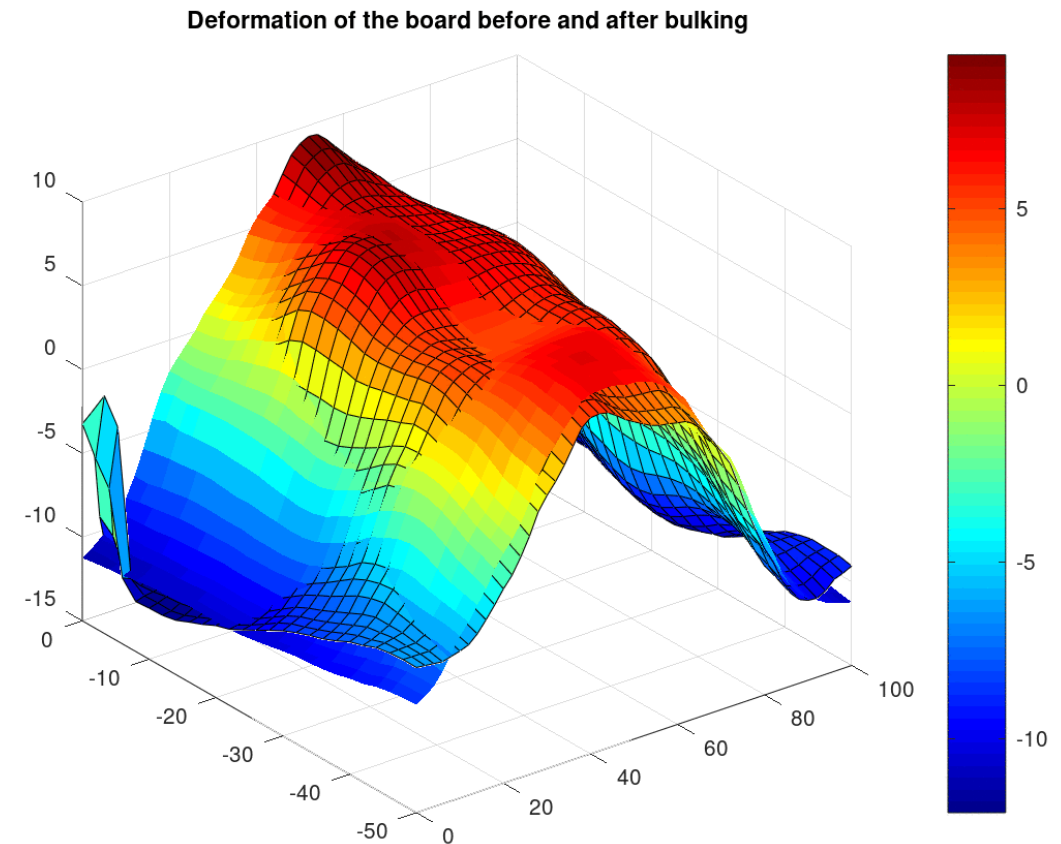


Height range around 30  $\mu\text{m}$

Height almost the same as before bulking

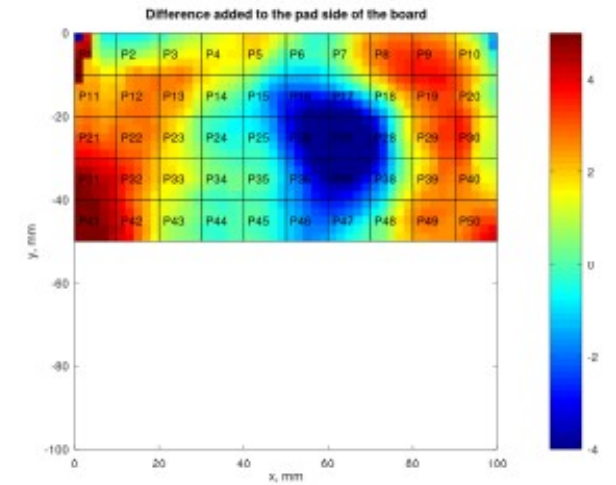
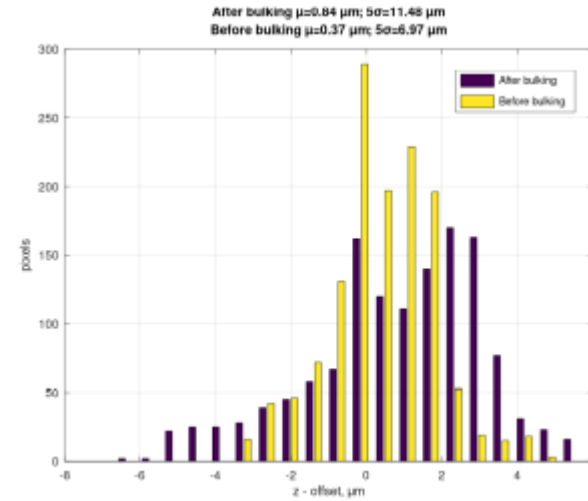
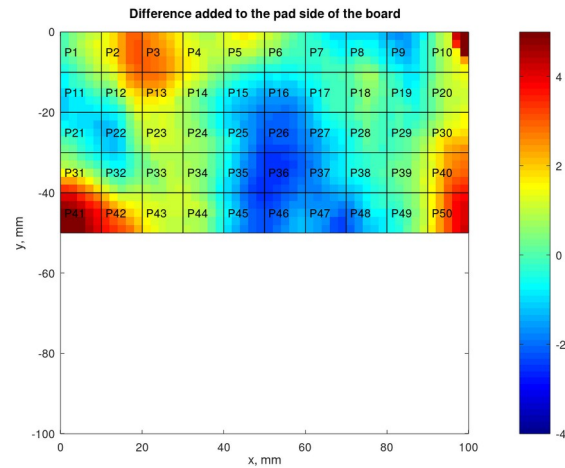
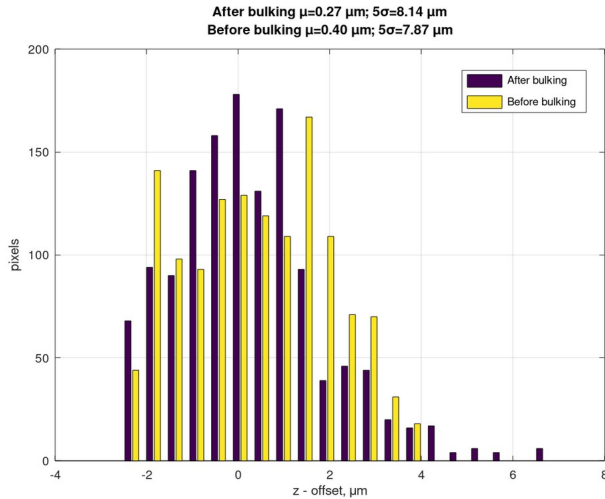
# How to interpret back side measurements

- **Very rough estimation:**
  - The deformations have propagated through the board on the top side, the thickness of the board is preserved.
  - Due to the MESH it is not possible to make planarity measurements on the top side.
- **Procedure:**
  - Make before and after comparison analysis of the back side of the board.
  - Calculate the difference.
  - Add the difference to the height top side before bulking.





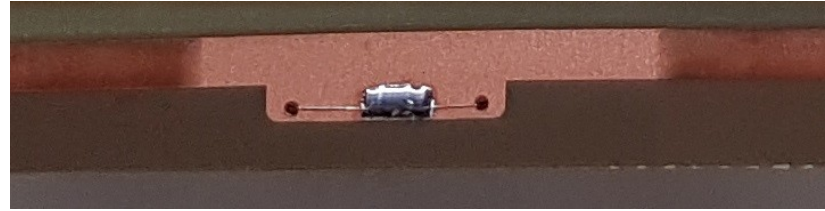
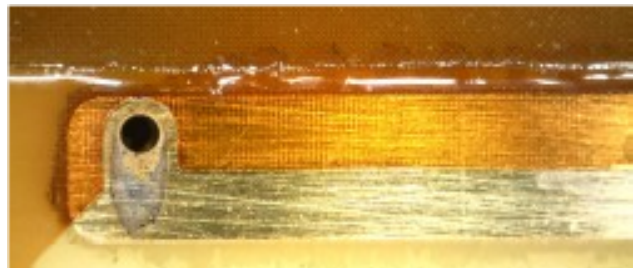
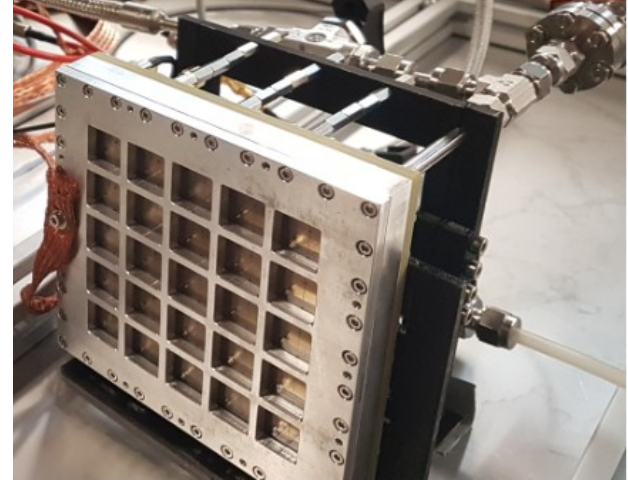
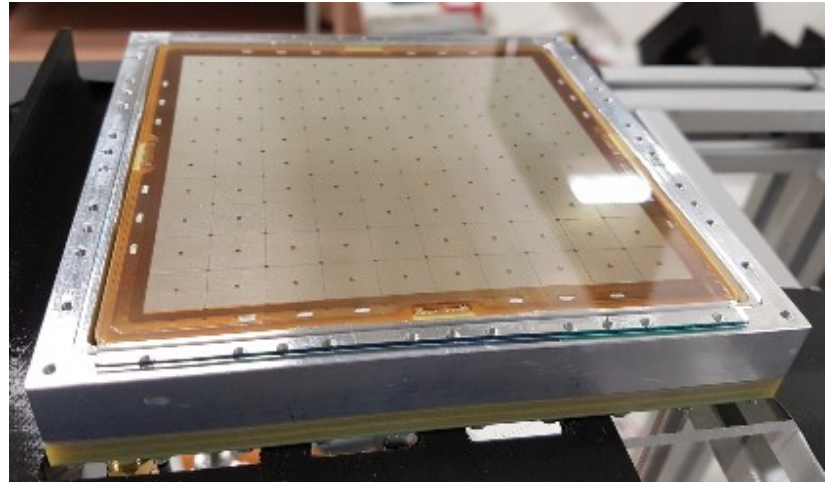
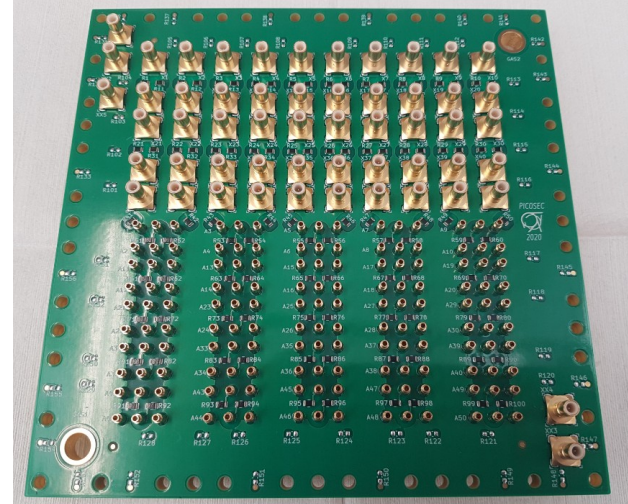
# Planarity of the board after bulking



- Planarity measurements of the backside after bulking show that there were **no large deformations due to the bulking process**.
- Analysis of the planarity measurement data shows that **a very rough estimation is that the overall planarity on the pads side is still below 10  $\mu\text{m}$** .
- Better information from the uniformity tests after detector assembly.

# Detector assembly: first HV and gas tightness tests

- HV stability test of the Outer board: cathode, anode and MESH connections stable up **1300 V**.
- HV stability test of the MM board (in air):
  - Anode: applying the voltage to all pads → **stable up to 900 V**
  - Cathode connection: **stable up to 900 V**
- Mounting the flange with Cr coated MgF<sub>2</sub> window and closing the chamber.
- Chamber leak rate: 2.1e-5 mbar l / s.





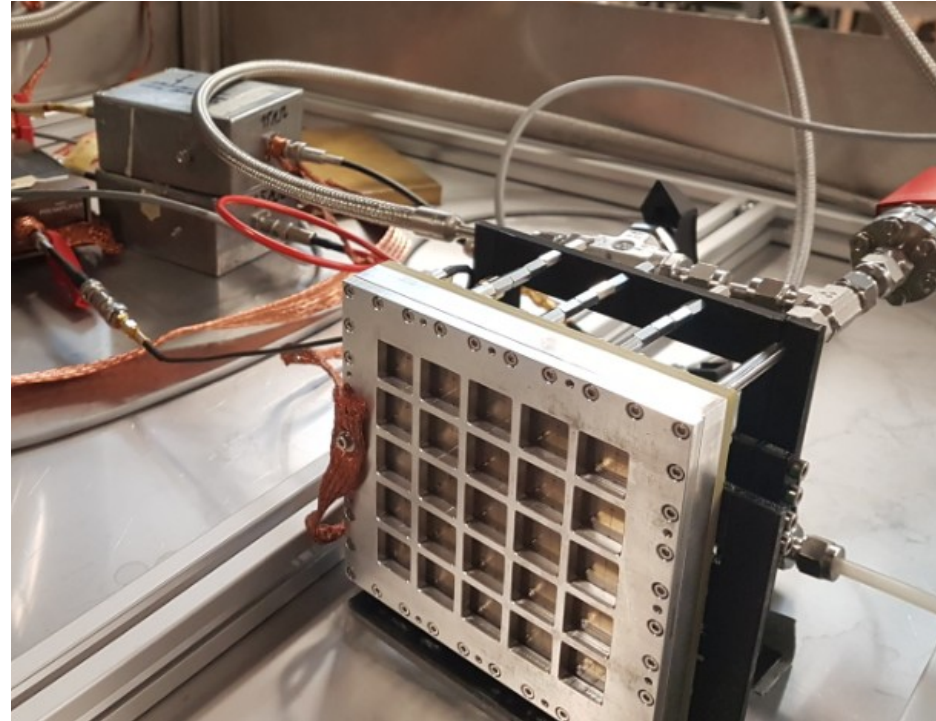
# New multipad PICOSEC: Hello world

MgF<sub>2</sub>

Chromium photocathode

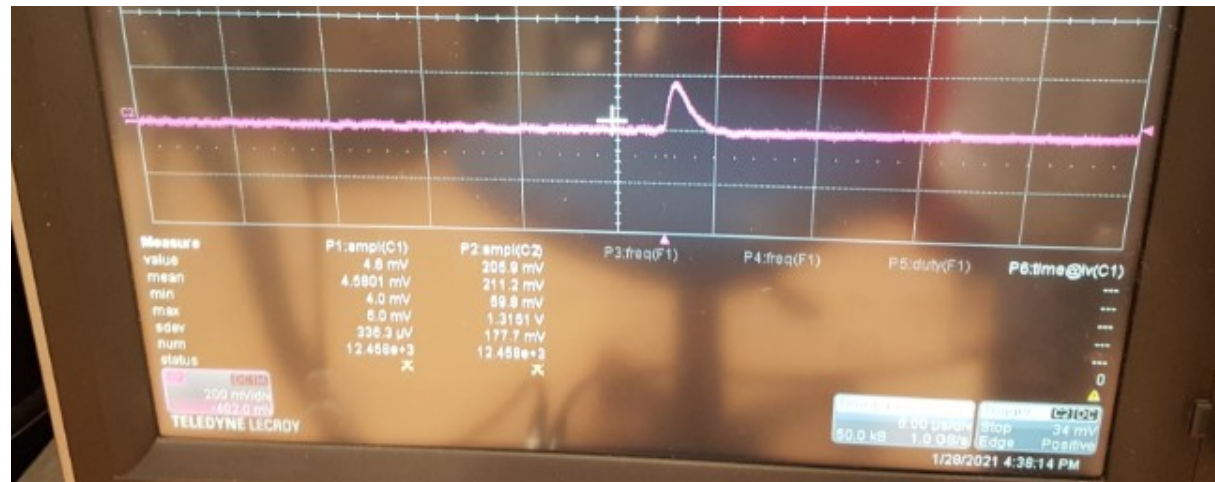
Mesh

Anode



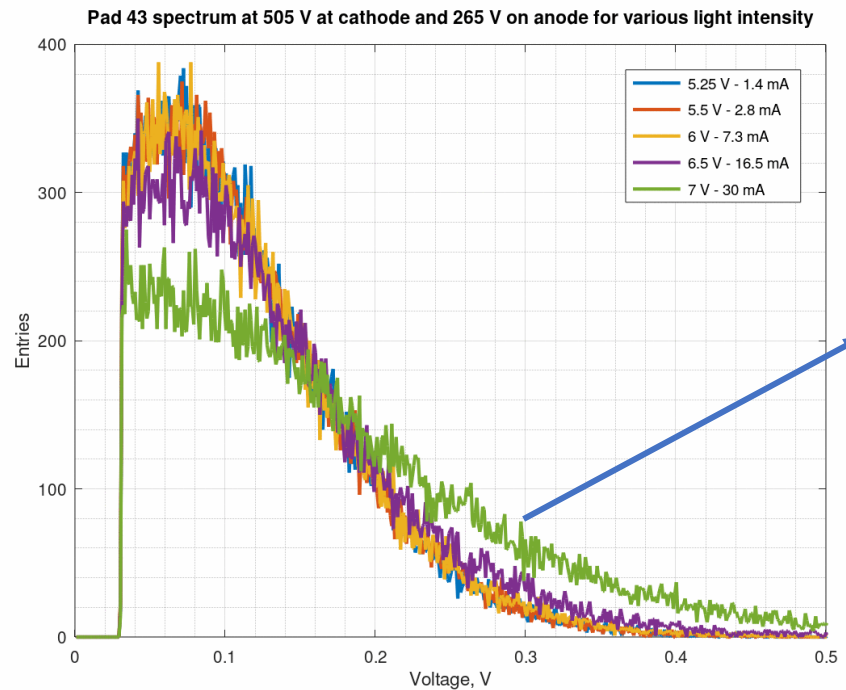
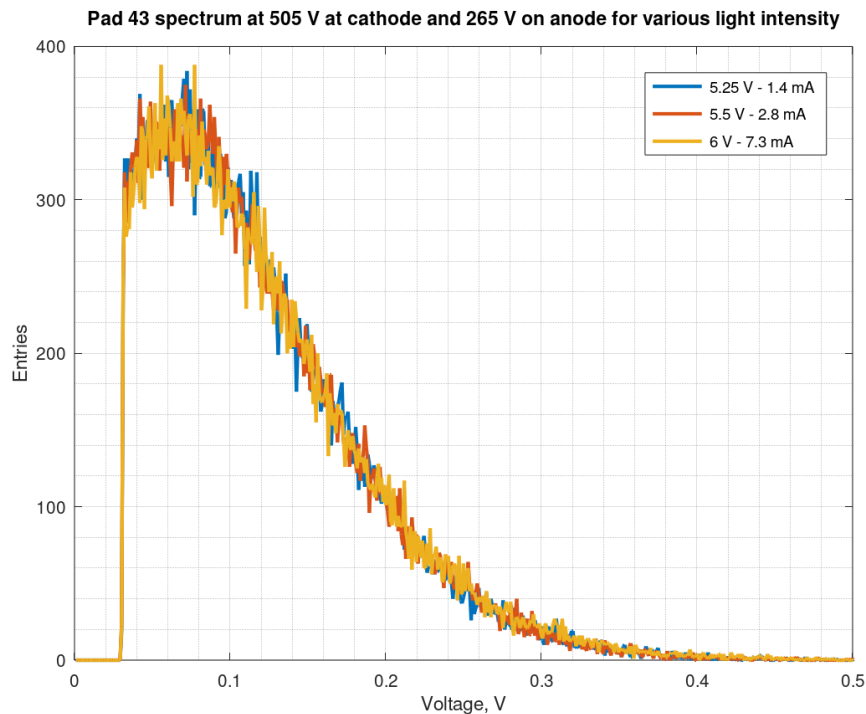
## Measurement equipment:

- Ortec 142 IH preamplifier.
- Ortec 474 timing filter amplifier.
- Caen N471A PS.
- MCA 8000D.
- UV diode-240 nm (model: UVTOP240TO18BL).
- Collimator ( $\phi=2\text{mm}$ ) 5 cm long to contain the light within one pad.



# First spectrum

- Measurements with different diode light intensity and fixed detector gain were made to have single p.e condition.
- Diode current was increased until difference in spectrum was observed.
  - For LED current above cca. 30 mA the spectrum shape changes significantly.
  - It is possible that the time between two consecutive single p.e events is shorter than the shaping time of the amplifier causing signal pile-up.
  - These events could be resolved in time in measurements with a fast preamplifier. ...to be done soon.
- Gain uniformity measurements were made with small LED light intensity in order not to have signal pile-up.

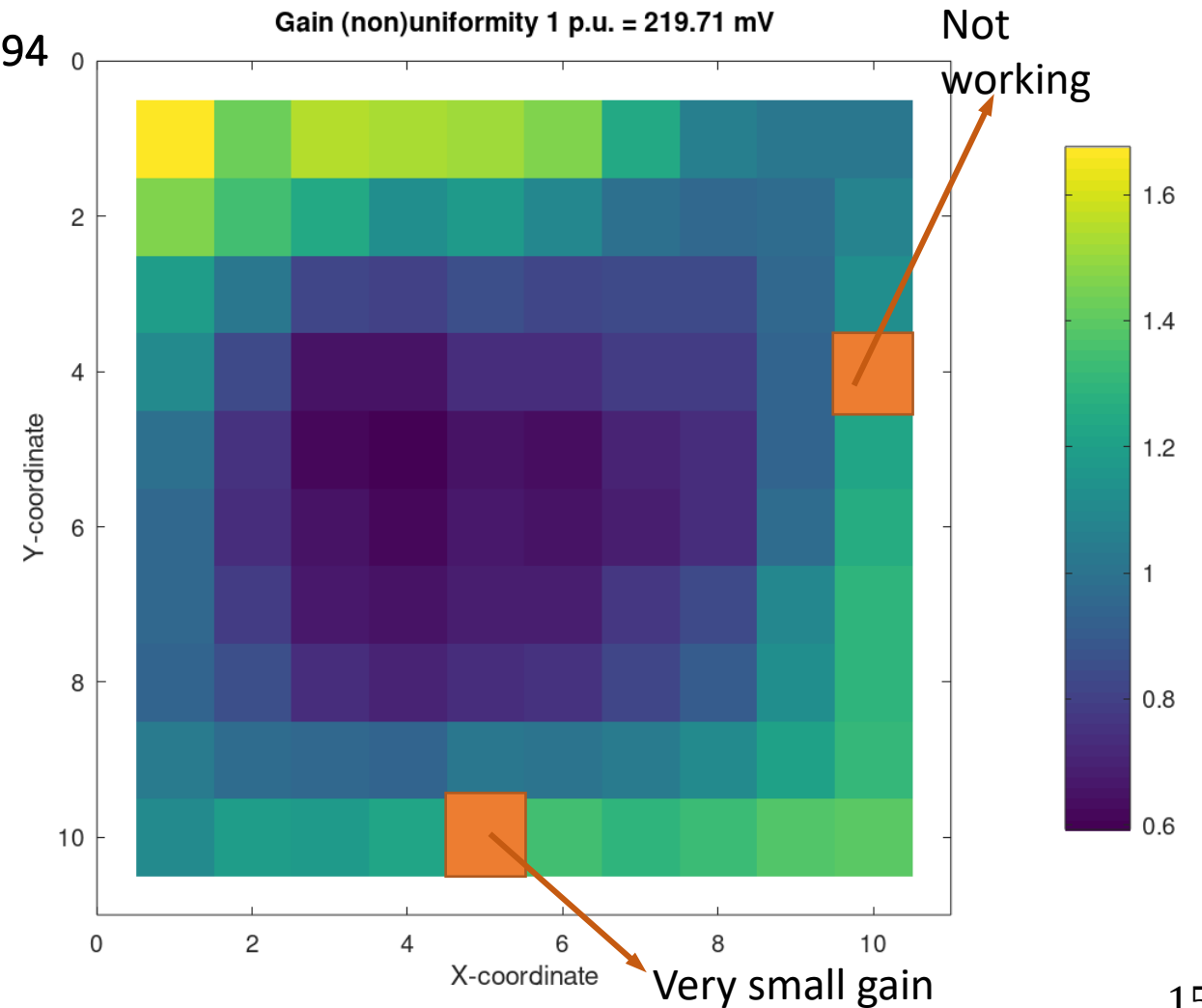
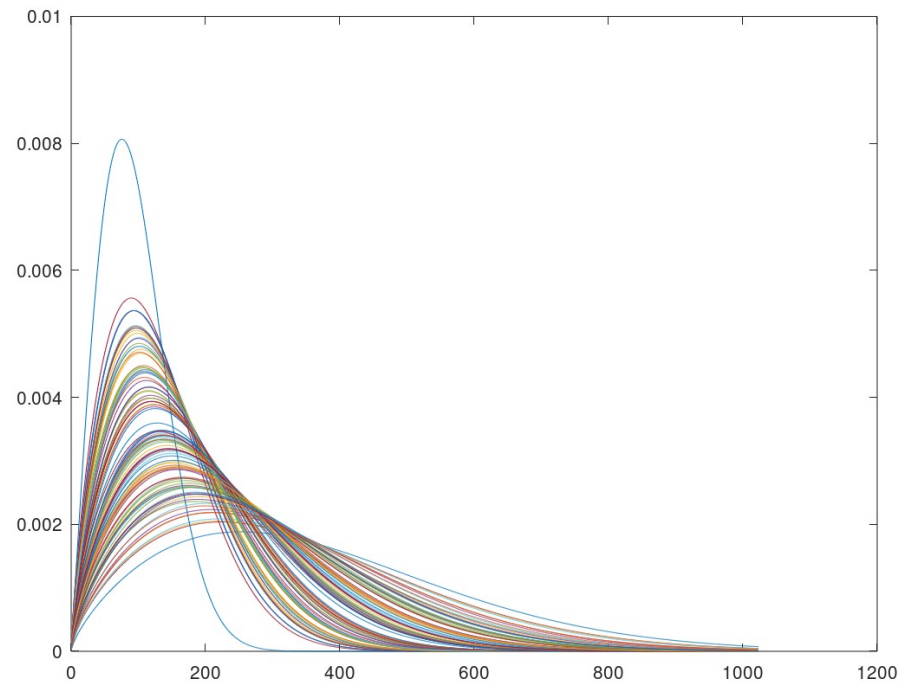


Lot of pile-up events after shaper.



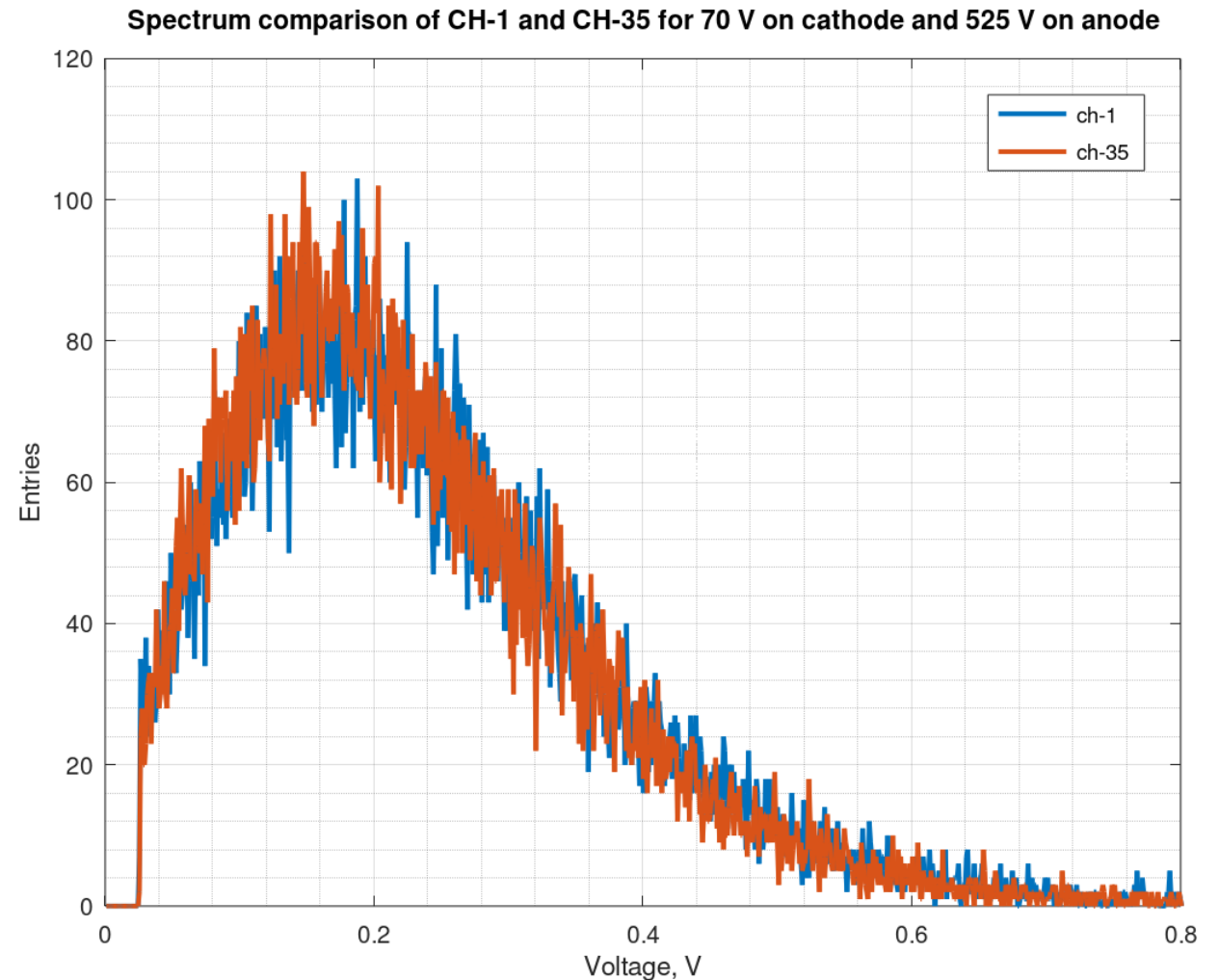
# Gain uniformity measurements in sealed mode

- Cathode voltage: 525 V
- Anode voltage: 265 V
- Problem with 2 channels (orange color on map): **channel 94** is not working and **channel 50** has very low gain.
- Polya fit was used to extract the mean of the spectrum.
- Large variation in gain observed



# Gain uniformity measurements in sealed mode

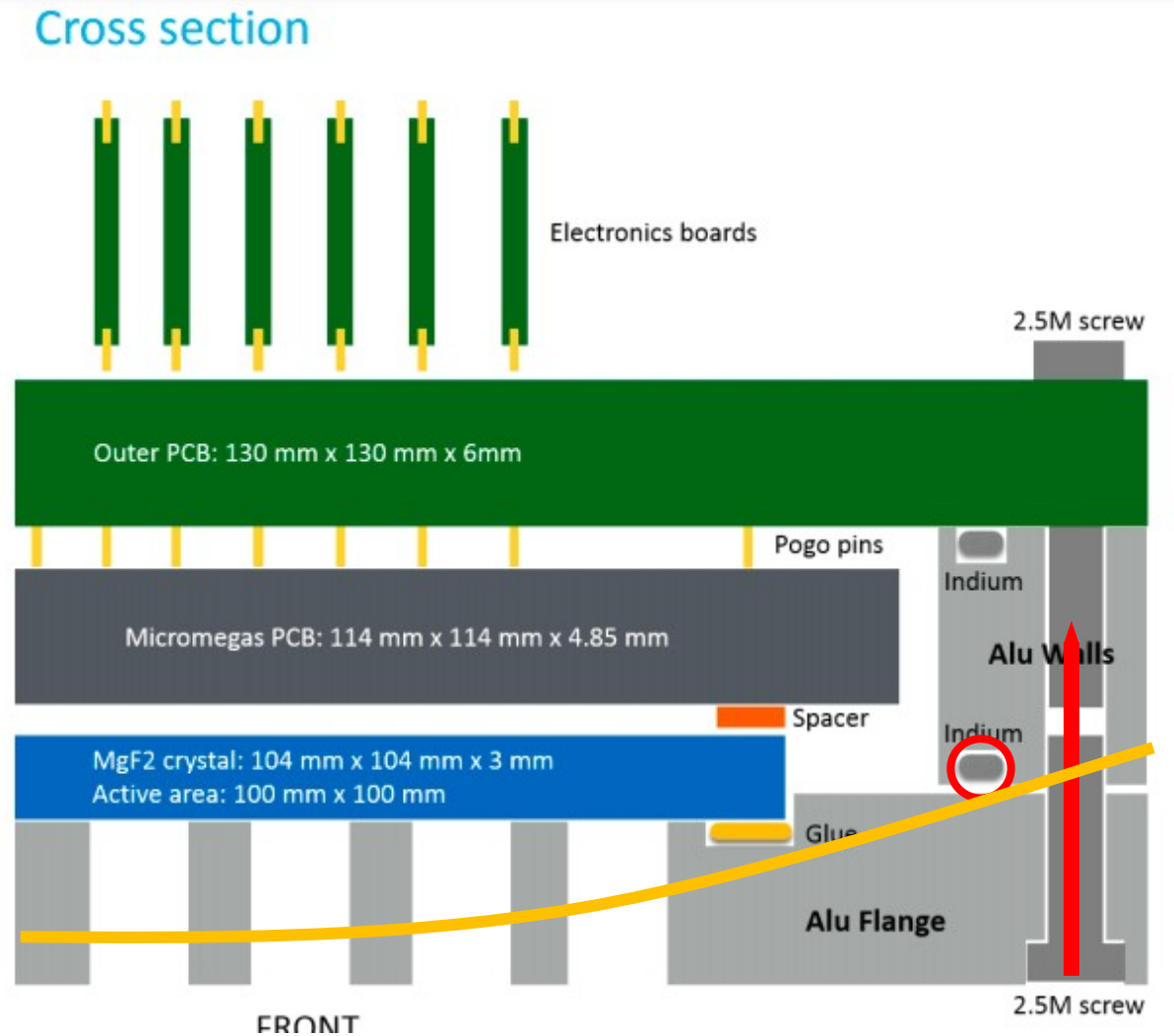
- Cathode: 70 V
- Anode: 525 V
- Gain comparison of the pads with the largest gain difference in the previous test ( CH-1 and CH-35).
- Gain is uniform- excludes possible non-uniformities from the mesh.
- The gain non-uniformity comes from the preamplification region – uneven preamplification gap.





# Sources of the gap-nonuniformity

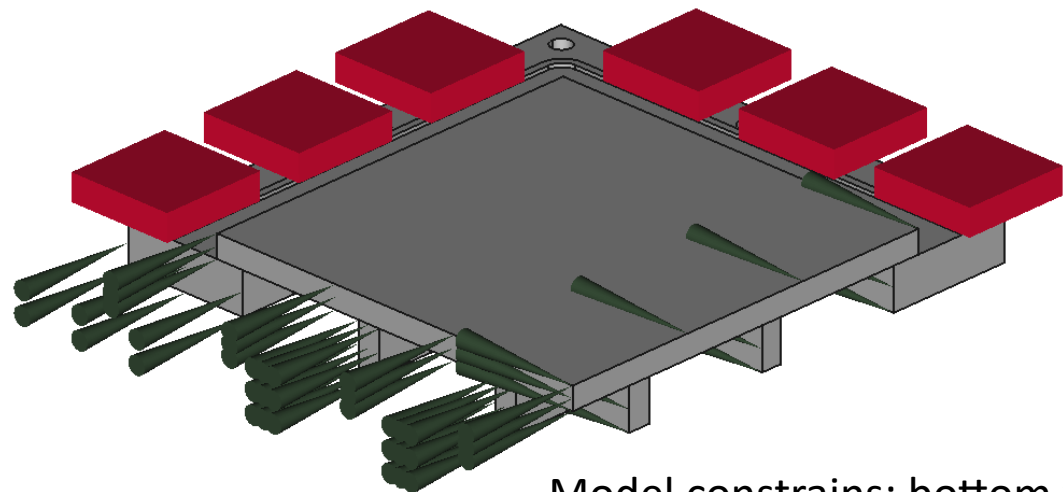
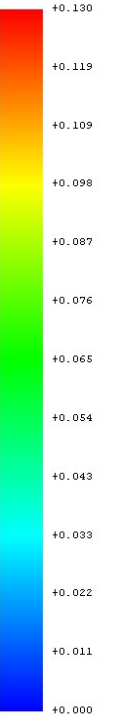
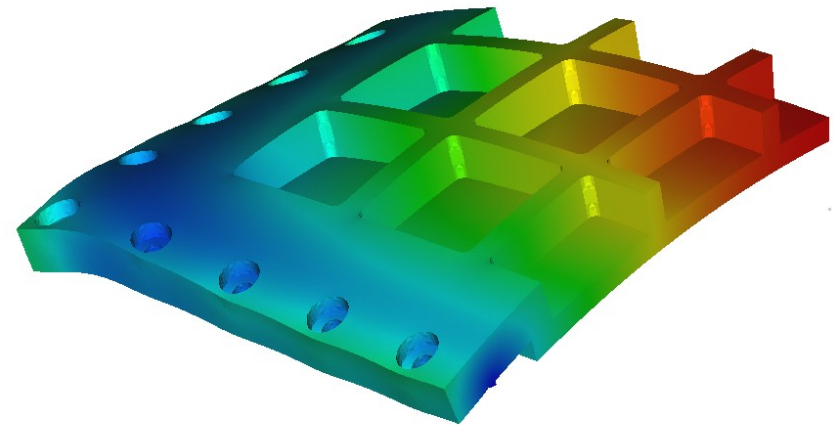
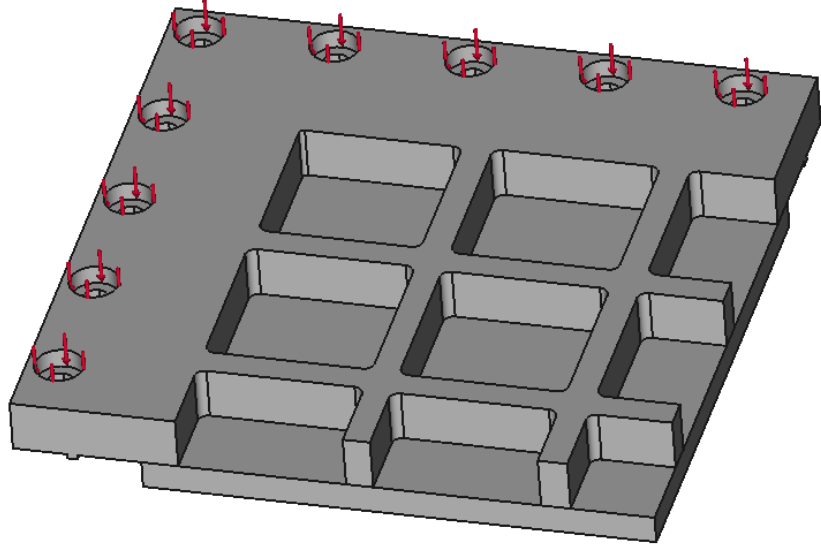
- Micromegas board is fully decoupled from housing and thoroughly tested to flatness specs.
- $\text{MgF}_2$  crystal is glued to the aluminum flange that is tightened with M2.5 screws to the chamber housing.
- Pressing force from each M2.5 screw torqued to 0.6 Nm is around 119 kg.
- Total:  $36 \times 119 \text{ kg} = 4284 \text{ kg}$ .
- $\text{MgF}_2$ :
  - Poisson ratio: 0.276
  - Youngs modulus: 138 GPa
- Aluminum
  - Poisson ratio: 0.33
  - Youngs modulus: 69 GPa
- Flange can bend over the Indium o-ring when being pressed with the screws.



More details on new PICOSEC module: Marta Lisowska, RD51 CM October 2020, <https://indico.cern.ch/event/889369/sessions/355853/#20201009>

# Sources of the gap-nonuniformity

Applied force: top view



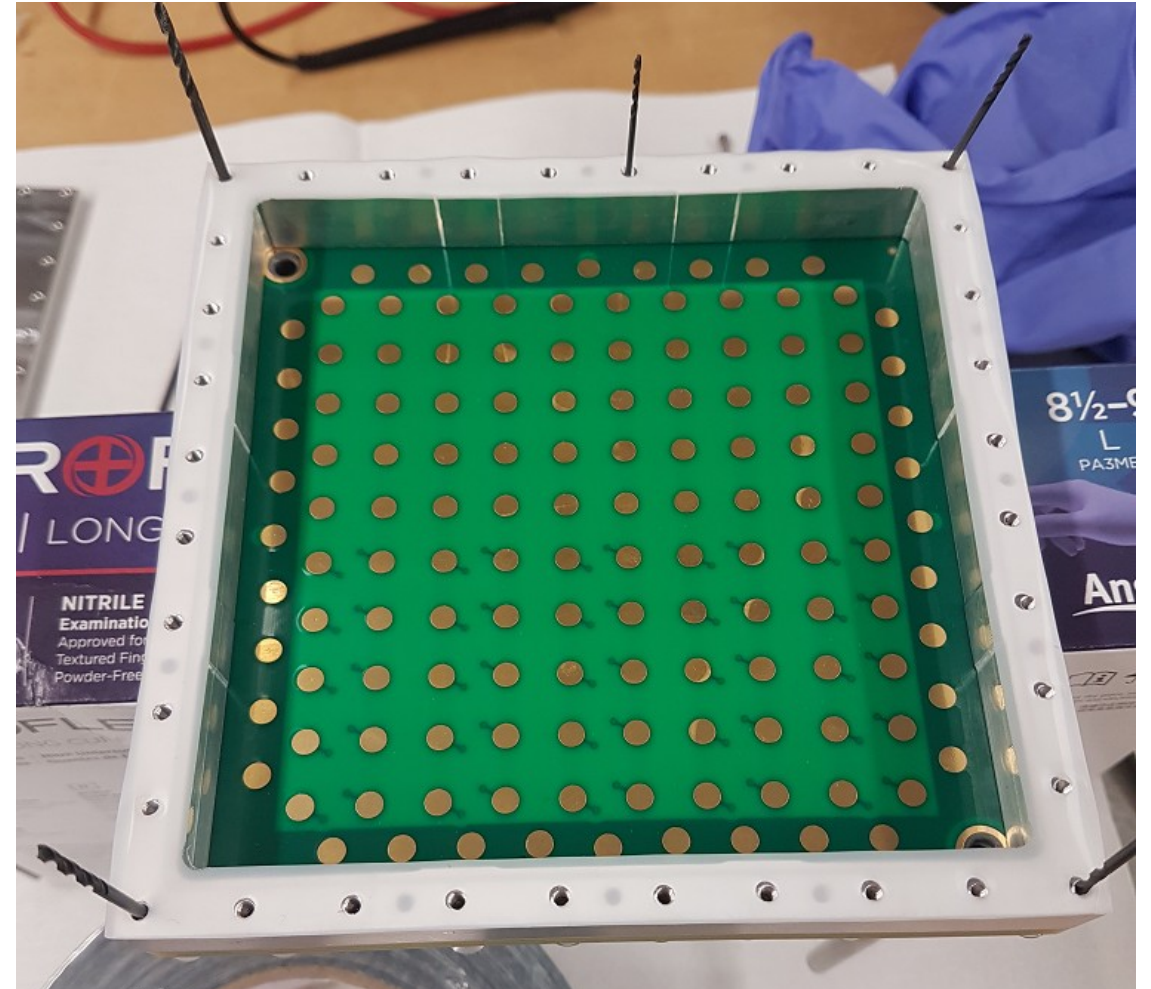
Model constrains: bottom view

- Displacement has a similar shape as the gain non-uniformity.
- Deformation is in the range of 130  $\mu\text{m}$ .
- Minimal deformation is at the corner and maximal displacement is in the crystal center.



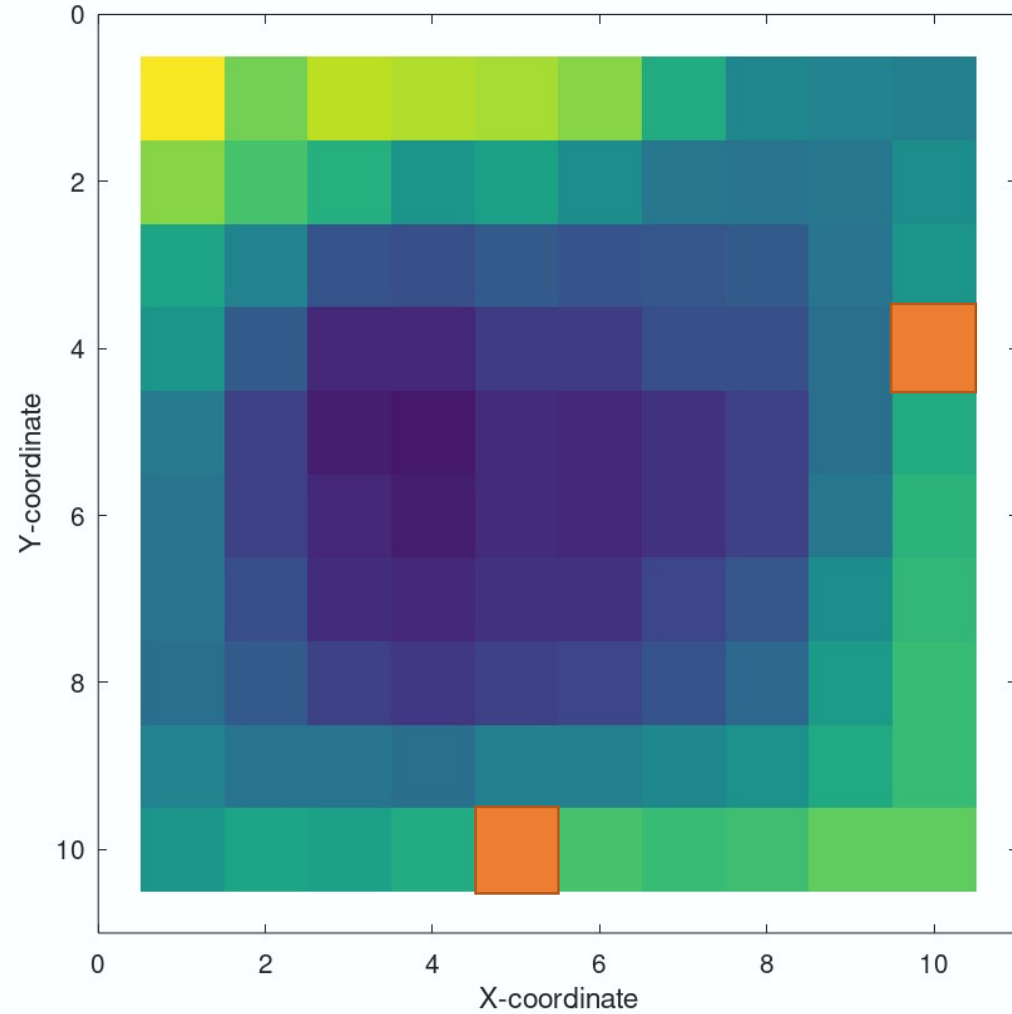
# Test with the flat PTFE gasket

- To test if the crystal is bending over the indium gasket, a replacement flat gasket was made.
- Gasket was made out of 0.1 mm thick PTFE sheet.
- The PTFE gasket was mounted only on the side of the crystal. The PCB with the connectors was still sealed using indium o-ring.
- PTFE gasket was uniformly torqued to 0.6 Nm.



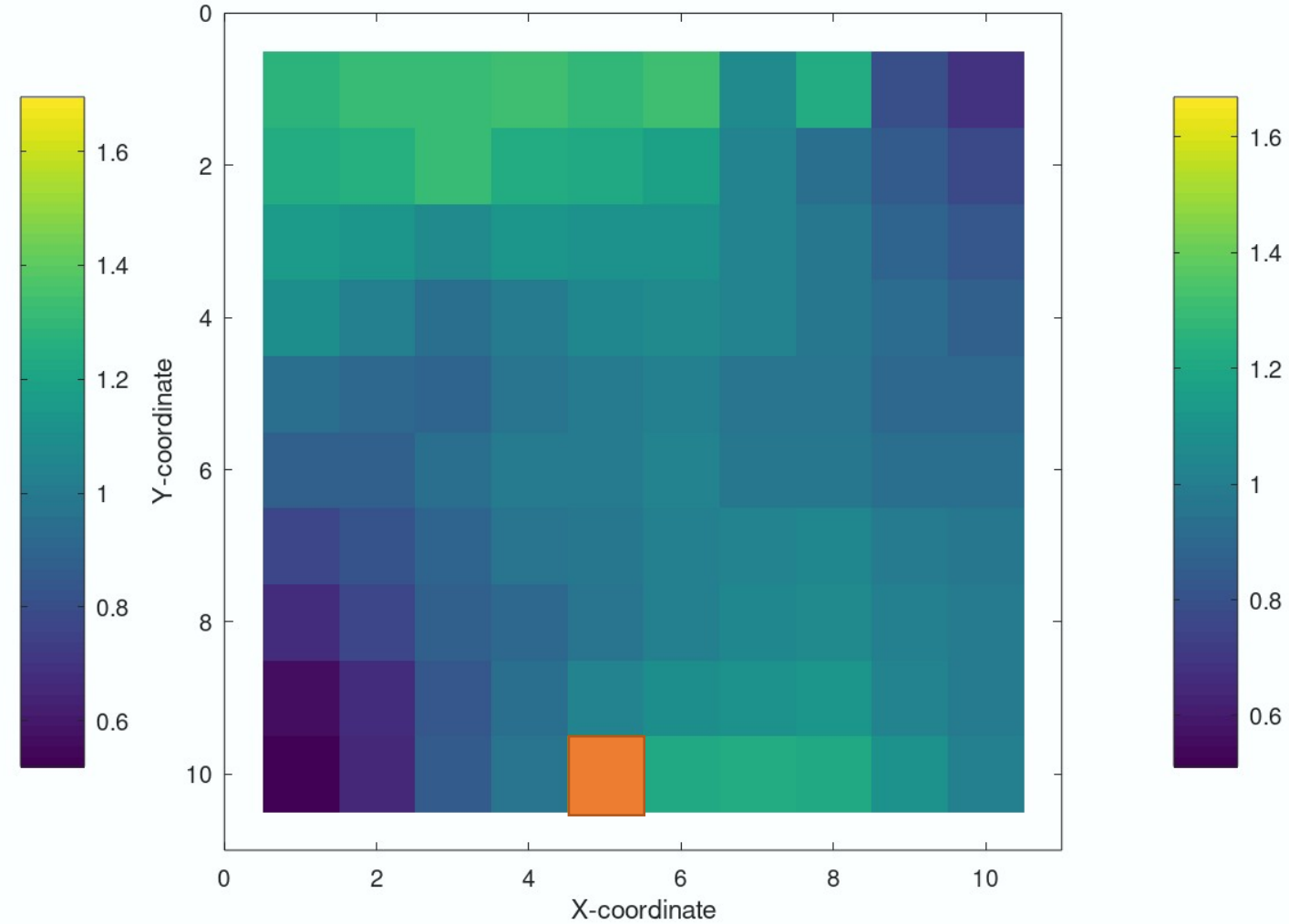
# Comparison of uniformity o-ring vs. flat gasket

Gain (non)uniformity 1 p.u. = 217.15 mV



**O-ring nonuniformity:  $\sigma = 28\%$**

Gain (non)uniformity 1 p.u. = 304.33 mV



**Flat gasket nonuniformity:  $\sigma = 16\%$**



# Conclusion

- Production of the embedded ceramic Micromegas was successfully finalized.
- Detector was assembled and the first tests show stable operation.
- **Planarity issues:**
  - The gain mapping of the detector showed poor gain uniformity. It was found out that it comes from the preamplification region.
  - Mechanical simulation suggests that the possible reason is the bending of the flange and the crystal.
  - Reassembly of the detector with the flat PTFE gasket resulted in a significantly different gain uniformity figure.
  - It is most likely that gain uniformity will not be fixed by the alternation of the flange sealing and the crystal should be also mechanically decoupled from the casing.
  - Modification of the casing and flange is necessary.

Thank you for your  
attention 😊

Questions?